

Supplementary Materials

Adhesion enhancement of ink-jet printed conductive copper patterns on a flexible substrate

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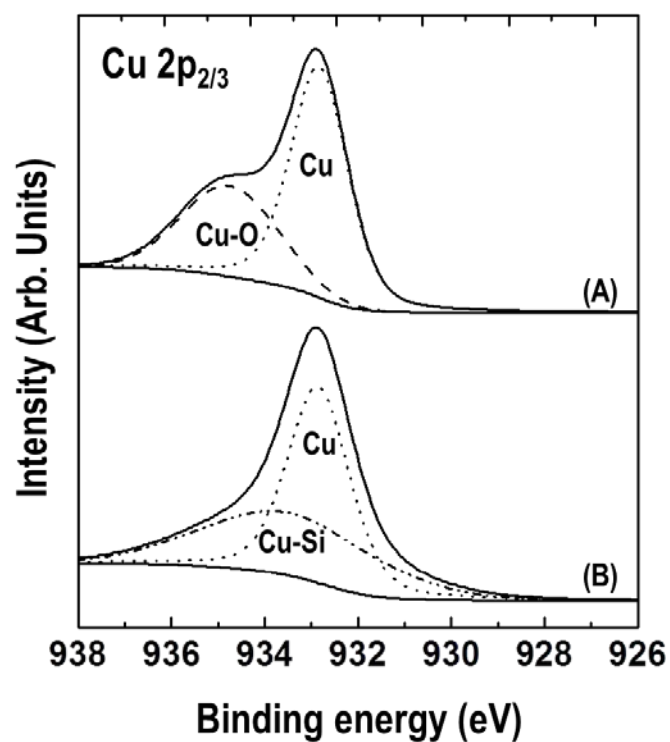


Fig. S1. XPS spectra showing Cu 2p_{3/2} states in ink-jet printed Cu films fabricated from Cu complex ion ink (A) without and (B) with APS.